

第十三届国际柔性电子大会 (ICFPE) 暨第五届柔性电子产业发展大会

THE 13TH INTERNATIONAL CONFERENCE ON FLEXIBLE AND PRINTED ELECTRONICS
AND THE 5TH FLEXIBLE ELECTRONICS INDUSTRY DEVELOPMENT CONFERENCE

26th-27th October, 2023

Chengdu • China

Homepage: <https://icfpe-cd.feidac.cn/>

HOSTED BY

Flexible Electronics Industry Development Alliance
The Management Committee of Chengdu High-tech Industrial and Development Zone

ORGANIZED BY

Chengdu High-tech Zone Electronic Information Industry Bureau
Nandu Media Co., Limited

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2023 General Chair

Wei Huang

Academician of CAS,China

2023 General Co-Chair

Takao Someya

The University of Tokyo, Japan



A WELCOME MESSAGE

Dear respected guests, experts, scholars, and entrepreneurs:

Hello! It is my great honor to invite you to participate in the 13th International Conference on Flexible and Printed Electronics.

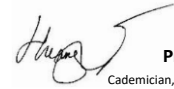
With the continuous development of technology and society, flexible and printed electronics has become one of the fastest-growing and most widely applied emerging technologies in recent years. As partners in this field, we all understand the enormous potential and broad prospects of this technology. Therefore, I believe that this conference will be an important platform for gathering talents, exchanging ideas, and exploring the future development direction of flexible and printed electronics.

I hope that this conference will provide participants with a broad, in-depth, and inspiring platform for communication, allowing everyone to share the latest progress and cutting-edge research results, explore important trends and frontier technologies in the future of flexible and printed electronics, promote industry-university-research cooperation, and drive innovation and application of flexible and printed electronics technology.

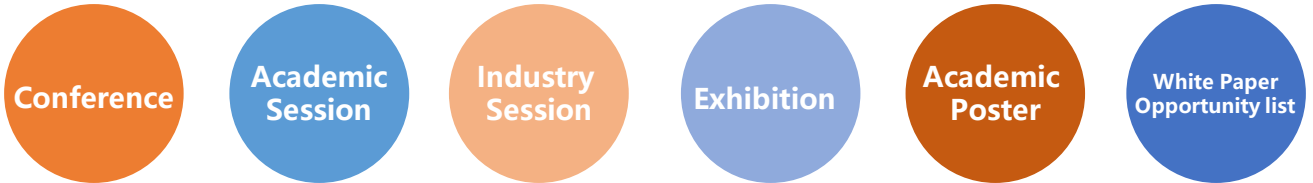
Finally, I would like to express my gratitude to all the guests, experts, scholars, and entrepreneurs who participated in this conference for their support and contributions. The fact that this conference is being held in Chengdu, China, it will mark a new height in the development of flexible and printed electronics in China.

I wish this conference a complete success! Let us work together for the further development of flexible electronics technology! Thank you all!

Professor Dr Takao Someya
The University of Tokyo, Japan



Professor Dr Wei HUANG
Academician, Chinese Academy of Sciences (CAS)
foreign academician of the Russian Academy of Sciences
foreign academician of the American Academy of Engineering
President, FEIAP
Chairman of the Academic Committee, Northwestern Polytechnical University



ICFPE Main Forum

Authority ace / Industry ace



Wei Huang
Academician of CAS, China



Takao Someya
The University of Tokyo, Japan



Dae-Hyeong Kim
Seoul National University, Korea



Ching W. Tang
Member, United States National Academy of Engineering, USA



Jianfeng Xu
CTO, HUAWEI



Zhepeng Wang
Vice President, Lenovo



Benhong Tan
Chairman and CEO, Aviat



Klaus Hecker
The OE-A, Germany



-
LG



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BOE



-
Sony



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Samsung

Conference & Expo

2023

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Breakout-Sessions

Academic

I: Flexible Printed Electronic Materials and Devices

Academic Convenor: Zheng Cui, Luhai Li, Wenyong Lai



II: Flexible Inorganic Thin Film Electronic Devices

Academic Convenor: Yuan Lin



III: Flexible Bioelectronics and Health Care

Academic Convenor: Fengwei Huo, Zhiyuan Liu



IV: Flexible Intelligent Sensing and Detection

Academic Convenor: Ting Zhang, Xuwen Wang



PLENARY SPEAKERS (The list is being continuously updated.)

The deadline for submitting papers and speech applications is August 31st.

Jie Zhang

Jiangnan University, China,

Ting Zhang

Suzhou Institute of Nano-Tech & Nano-Bionics, CAS, China

Xiachang Zhang

Jiangsu Enfusai Flexible Electronics Co., Ltd, China

Gyoujin Cho

Sungkyunkwan University, Korea

Vincent C. Lee

National University of Singapore, Singapore

Keizo KATO

Niigata University, Japan

Ying-Chih Liao

National Taiwan University, Taiwan, China

Chih-I Wu

National Taiwan University, Taiwan, China

Changqi Ma

Suzhou Institute of Nano-tech and Nano-bionics (SINANO), China

Wenbo Li

AECC BIAM, China

Lixin MO

Beijing Institute of Graphic Communication, China

Weiwei LI

Northwestern Polytechnical University, China

Breakout-Sessions

Industry (The ranking is not in any particular order.)



PLENARY SPEAKERS (The list is being continuously updated.)

Xingye Zhang

Beijing Dahua Boke Intelligent Technology Co. , China

Jing Liu

Beijing DREAM Ink Technologies Co., Ltd. , China

Jian Lin

Guangdong Green Prosperity Technology CO., Ltd., China

Daping Cao

Jire Technology Co., Ltd., China

Sichao Dong

Hunan NanoUp Electronics Technology Co., Ltd., China

He Lan

Shanghai Mifang Electronic Technology Co., Ltd., China

Toshinori Fujie

Tokyo Tech, Japan

Taik min Lee

Korea Institute of Machinery and Materials , Korea

Kyung tae Kang

Korea Institute of Industrial Technology , Korea

Chuan-Chuan Tsai

AUO Corp , Taiwan , China

Xiachang Zhang

Enfusai Flexible Electronics Co.,Ltd , China

An jung Chung

Korea Flexible&Printed Electronics Association, Korea

Toshihide Kamata

AIST, Japan

Jupiter Hu

Industrial Technology Research Institute, Taiwan, China

Boon Keng Lok

SIMTech, Singapore

Shan Xuechuan

SIMTech, Singapore

Registration guide

(Please register and pay through the <https://icfpe-cd.feidac.cn/>)

Academic Session Registration Fee

	Early-bird (~ July 31, 2023)		Standard	
	International	Domestic	International	Domestic
Regular	207 USD	1428 RMB	243 USD	1680 RMB
Student	109 USD	748 RMB	128 USD	880 RMB

- The registration fee includes admission to all Academic Session , Conference materials, lunches(2days)

Exhibition Fee

Type	Size	Cost
Minimal	Special Booth, 8m ²	10000 RMB
Standard	Special Booth, 30m ²	30000 RMB
Academic Poster	16:9	Only open to registered participants of the academic session.

- The illustrations may be slightly different, in terms of the open sides, from the actual booth, depending on the exact allocation at the exhibition area.



Minimal



Standard

Payment

	International	Domestic
Beneficiary	Nandu Future Creative Technology (Chengdu) Co., Ltd.	南都未来创意科技（成都）有限公司
Beneficiary's Address	13-3/F, China Overseas International Center Block F, No.365 Jiaozi Avenue, High-tech District Chengdu	/
SWIFT CODE (BIC)	CMBCCNBS	/
Beneficiary's Bank	China Merchants Bank, H.O.Shenzhen, China	招商银行股份有限公司成都天府大道支行
Account Number	128910100510701	128910100510701
Bank Address	China Merchants Bank Tower NO.7088, Shennan Boulevard, Shenzhen, China	/

- lease note any bank fees, including those from originating or intermediary banks, should be borne by the applicants.
- If the remittance covers more than one person, please inform us of the name for each participant.
- If you require an invoice for the payment, please contact the Registration Office.

Conference & Expo

2023

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Please contact us for more information.

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